

(C) WPI/Derwent

AN - 1981-78326D [25]

A - [001] 011 04- 040 141 150 151 157 199 220 221 226 231 232 233 273 316  
332 336 341 359 398 400 431 440 442 446 473 477 481 483 597 600 609  
657 664 720

CPY - TOKE

DC - A14 A21 A81 F09 G03

FS - CPI

IC - C09J5/02 ; D21H1/04

KS - 0016 0218 0231 1282 1283 1294 1373 1601 1992 2020 2198 2295 2318 2427  
2434 2436 2488 2493 2507 2524 2528 2659 2682 2723 2725 2801 2819

MC - A05-A01E1 A05-F A05-G01E A08-D03 A11-B05D A11-C02 A12-A05F A12-B03  
A12-W06A F05-A06 F05-A06B G02-A05C G02-A05E G03-B03

PA - (TOKE ) TOKYO SHIBAURA ELECTRIC CO

PN - JP56058094 A 19810520 DW198143 003pp

PR - JP19790129480 19791009

XIC - C09J-005/02 ; D21H-001/04

AB - J56058094 Coating soln. (I) is prepd. by diluting epoxy resin in organic solvent e.g. MeOH. (I) is coated on the surface of aramid paper, e.g. Nomex paper (Du Pont), using aliphatic amine as hardener. The epoxy resin contains 7-10wt.% of polyvinyl butyral with butylation degree of 50-70%. Upon curing of the resin and formation of primer film, the aramid paper is bonded to substrate using polyurethane resin adhesive.

- Aramid paper which has poor surface reactivity is strongly bonded to substrates even at low temp.

- Formulation comprises e.g. epoxy resin (Epicote 828 - Shell) 100 pts.wt., hardener (HY956 - Ciba) 25 pts.wt., butyral (Ester B - SEKI) 14 pts.wt., methyl alcohol 300 pts.wt. Tensile test showed that delamination occurred with Nomex paper at 28.0 kg/cm<sup>2</sup> but there was no sepn. between polyurethane adhesive and the surface of paper.

IW - COATING ARAMID PAPER POLYEPOXIDE RESIN SOLUTION ADHERE SUBSTRATE  
POLYURETHANE RESIN IMPROVE ADHESIVE OBTAIN

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NC - 001

OPD - 1979-10-09

ORD - 1981-05-20

PAW - (TOKE ) TOKYO SHIBAURA ELECTRIC CO

TI - Coating aramid paper with epoxy] resin soln. - and then adhering to substrate using urethane] resin, improved adhesion is obtd.